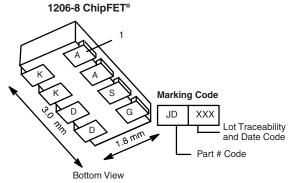




N-Channel 1.8 V (G-S) MOSFET with Schottky Diode

MOSFET PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A)			
	0.040 at V _{GS} = 4.5 V	5.9			
20	0.045 at V _{GS} = 2.5 V	5.6			
	0.052 at V _{GS} = 1.8 V	5.2			

SCHOTTKY PRODUCT SUMMARY					
V _{KA} (V)	V _f (V) Diode Forward Voltage	I _F (A)			
20	0.375 V at 1.0 A	1.0			



Ordering Information: Si5856DC-T1-E3 (Lead (Pb)-free) Si5856DC-T1-GE3 (Lead (Pb)-free and Halogen-free)

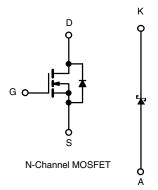
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFETs
- Ultra Low R_{DS(on)}
- Ultra Low V_F Schottky
- Si5853DC Pin Compatible
- Compliant to RoHS Directive 2002/95/EC

Pb-free RoHS COMPLIANT HALOGEN FREE Available

APPLICATIONS

- · Buck Rectifier Switch, Buck-Boost
- Synchronous Rectifier or Load
- Switch for Portable Devices



Parameter	Symbol	5 s	Steady State	Unit	
Drain-Source Voltage (MOSFET and Schottky)		V _{DS}	20		V
Reverse Voltage (Schottky)		V _{KA}	20		
Gate-Source Voltage (MOSFET)		V _{GS}	± 8		
Continuous Dusin Comment /T 150 90\ (MOSEET\)	T _A = 25 °C		5.9	4.4	
Continuous Drain Current (T _J = 150 °C) (MOSFET) ^a	T _A = 85 °C	I _D	4.2	3.1	
Pulsed Drain Current (MOSFET)		I _{DM}	20		٨
Continuous Source Current (MOSFET Diode Conduction) ^a		I _S	1.8	0.9	Α
Average Forward Current (Schottky)		I _F	1.0		
Pulsed Forward Current (Schottky)		I _{FM}	7		
Manifesture Device Dissipation (MOCEFT)	T _A = 25 °C		2.1	1.1	w
Maximum Power Dissipation (MOSFET) ^a	T _A = 85 °C	P _D	1.1	0.6	
Mariana Barra Biraina Kara (Onto III - N	T _A = 25 °C	' b	1.9	1.1	
Maximum Power Dissipation (Schottky) ^a	T _A = 85 °C		1.0	0.56	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150		°C	
Soldering Recommendations (Peak Temperature) ^{b, c}			260	C	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. See reliability manual for profile. The ChipFET is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- c. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.

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THERMAL RESISTANCE RATINGS								
Parameter		Device	Symbol	Typical	Maximum	Unit		
Junction-to-Ambient ^a	t≤5s	MOSFET		50	60			
	1 ≥ 3 8	Schottky	R _{thJA}	54	65			
	Steady State	MOSFET	' 'thJA	90	110	°C/W		
	Steady State	Schottky]	95	115			
Junction-to-Foot	Steady State	MOSFET	R _{thJF}	30	40	1		
Juli Ciloti-to-Foot	Sleady State	Schottky	' 'thJF	30	40			

Notes:

a. Surface mounted on 1" x 1" FR4 board.

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	•				•		
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.4		1.0	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
Zana Cata Maltana Busin Comment		V _{DS} = 20 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$			5	- μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	20			Α	
Drain-Source On-State Resistance ^a		$V_{GS} = 4.5 \text{ V}, I_D = 4.4 \text{ A}$		0.032	0.040	Ω	
	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, I_D = 4.1 \text{ A}$		0.036	0.045		
		$V_{GS} = 1.8 \text{ V}, I_D = 1.9 \text{ A}$		0.042	0.052		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 4.4 A		22		S	
Diode Forward Voltage ^a	V_{SD}	I _S = 1.0 A, V _{GS} = 0 V		0.8	1.2	V	
Dynamic ^b							
Total Gate Charge	Qg			5	7.5		
Gate-Source Charge	Q _{gs}	Q_{gs} $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 4.4 \text{ A}$		0.85		nC	
Gate-Drain Charge	Q _{gd}			1		1	
Turn-On Delay Time	t _{d(on)}			20	30		
Rise Time	t _r	V_{DD} = 10 V, R_L = 10 Ω		36	55		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 1 A, V_{GEN} = 4.5 V, R_g = 6 Ω		30	45	ns	
Fall Time	t _f			12	20		
Source-Drain Reverse Recovery Time	t _{rr}	$I_F = 0.9 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$		45	90		

Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

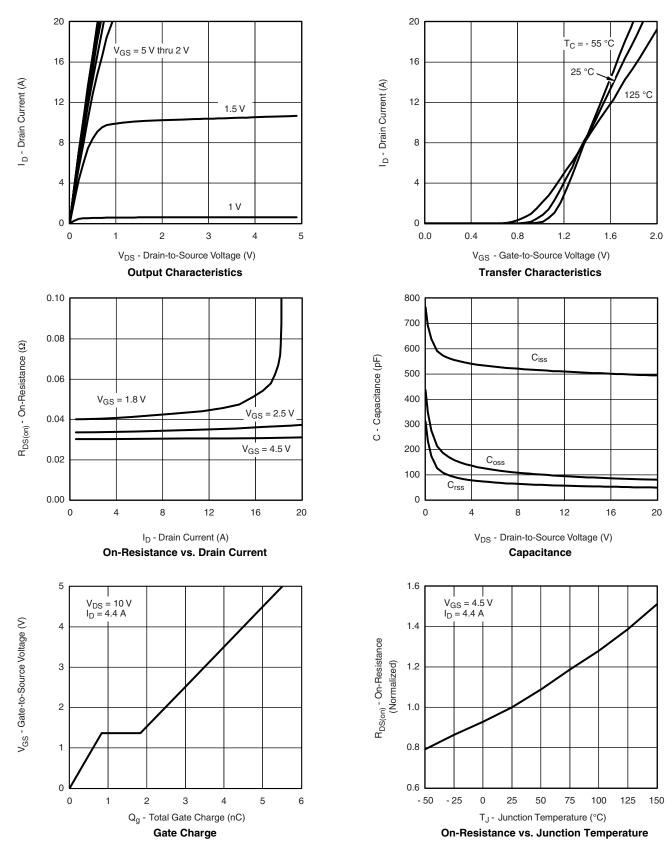
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

SCHOTTKY SPECIFICATIONS T _J = 25 °C, unless otherwise noted								
Parameter	Symbol	Test Conditions Min.		Тур.	Max.	Unit		
Forward Voltage Drop	V _F	I _F = 1.0 A		0.34	0.375	0.375 V		
		I _F = 1.0 A, T _J = 125 °C		0.255	0.290	V		
Maximum Reverse Leakage Current	I _{rm}	V _r = 20 V		0.05	0.500			
		V _r = 20 V, T _J = 85 °C		2	20	mA		
		V _r = 20 V, T _J = 125 °C		10	100			
Junction Capacitance	C _T	V _r = 10 V		90		pF		



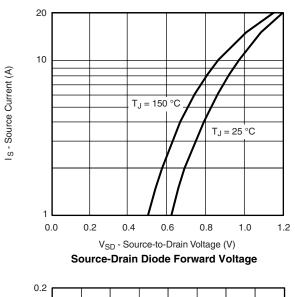


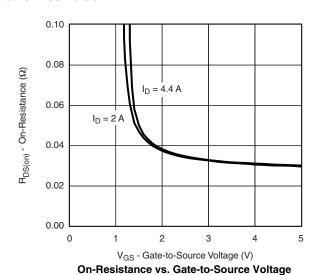
MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

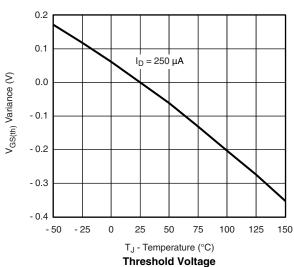


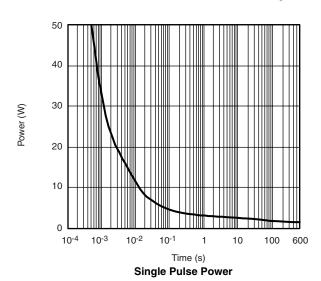
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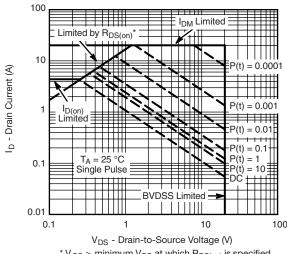
MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted









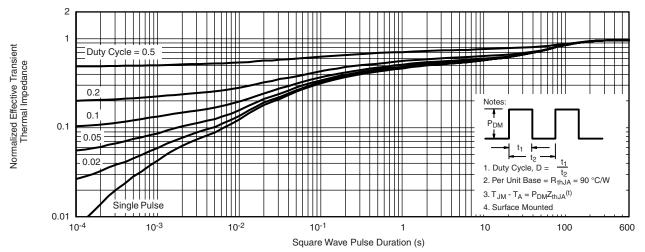


 $^*\,V_{GS}>$ minimum V_{GS} at which $R_{DS(on)}$ is specified

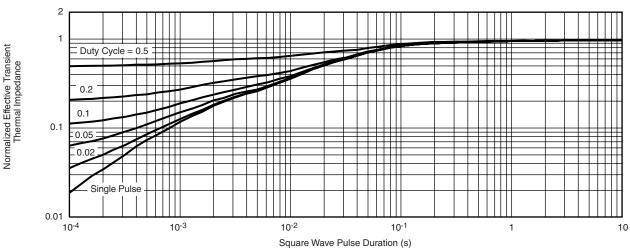
Safe Operating Area



MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

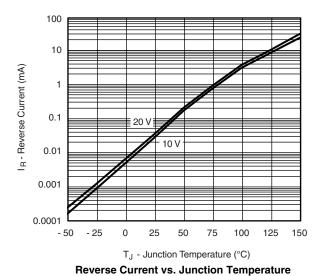


Normalized Thermal Transient Impedance, Junction-to-Ambient

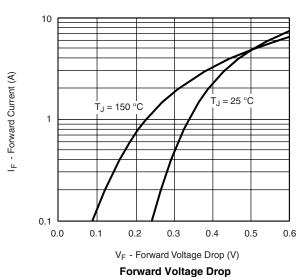


Normalized Thermal Transient Impedance, Junction-to-Foot

SCHOTTKY TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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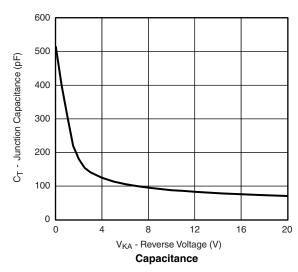


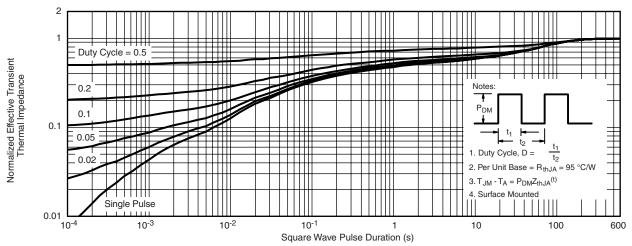
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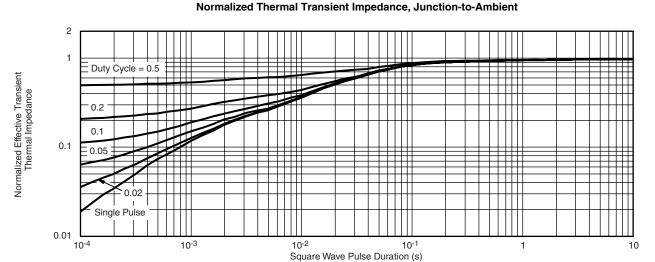
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SCHOTTKY TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted







Normalized Thermal Transient Impedance, Junction-to-Foot

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